

FLUX CORED WIRE SOLDER

2006A

Standard type

Featuring both excellent initial wettability
and solder workability.
Can be used for a wide variety of
soldering applications.

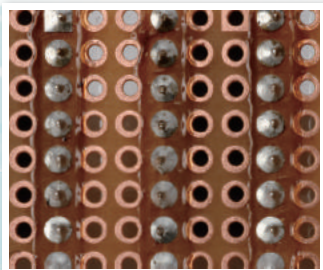
Fine Solder



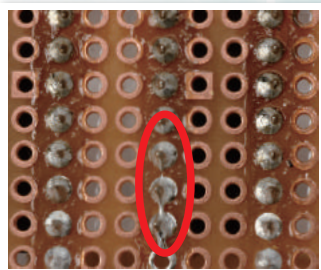
Product Features

■ Outstanding solder workability

We carried out testing in extremely harsh conditions with the soldering iron tip at 430°C, and the result showed that the adoption of the new activation agent helped significantly improve solder workability and inhibit the formation of solder bridges or icicles.



φ 2006A
MATSUO



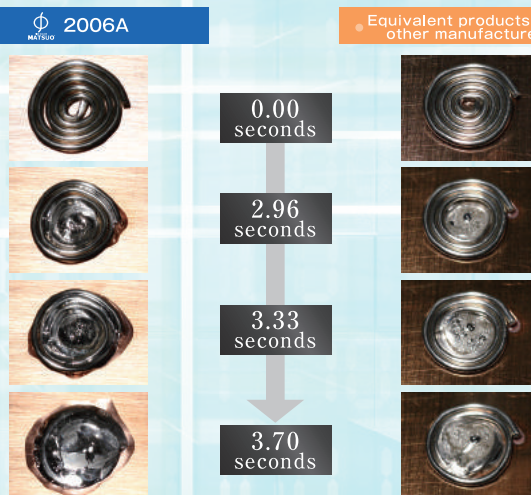
Equivalent products from
other manufacturers

■ Test conditions

- Pull speed : 7mm/sec
- Solder wire diameter : φ0.8mm
- Solder dispensing amount : 20mm/line
- Flux content : 3%
- Soldering iron tip temperature : 430°C

■ Initial wettability improved significantly

Initial wettability (melting speed) is now improved thanks to the improvement in flux. Excellent workability even at low temperatures.



■ Test conditions 260°C±5°C

Alloy no.	JIS mark	Alloy composition	Solidus temperature	Liquidus temperature	Wire diameter (mm)
FLF01	A30C5	Sn96.5%-Ag3.0%-Cu0.5%	Approx. 217°C	Approx. 219°C	φ0.3·φ0.4·φ0.5 φ0.6·φ0.8·φ1.0 φ1.2·φ1.6·φ2.0
FLF07	C7A3	Sn99.0%-Ag0.3%-Cu0.7%	Approx. 217°C	Approx. 226°C	
FLF03	C7	Sn99.3%-Cu0.7%	Approx. 227°C	Approx. 227°C	

Items	2006A	Specifications (Reference)
		JIS Z 3283/A grade
Alloy composition	FLF01/FLF03/FLF07	—
Flux content	3%	2.7% ~ 3.3%
Halide content	0.13%	0.1% ~ 0.5%
Aqueous solution resistance	700Ωm	> 500Ωm
Insulation resistance test (85°C 85%RH 168hr)	> 2×10 ⁹ Ω	> 1×10 ⁹ Ω
Migration test (85°C 85%RH 1,000hr)	Pass	No migration
Spread rate	75%	> 70%

